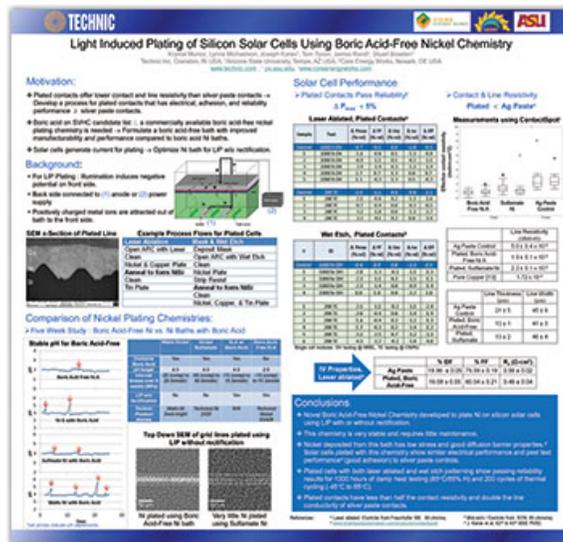


# Technic presents findings on Boric Acid-Free, Light Induced Nickel Plating at IEEE-PVSC Conference

Cranston RI - Technic presented *Light Induced Plating of Silicon Solar Cells Using Boric Acid-Free Nickel Chemistry* at the annual IEEE-PVSC Conference held in Washington DC on June 25-30.

Technic's research on boric-acid free nickel plating chemistry and the resulting performance on silicon solar cells be presented at the conference's poster forum. This ongoing research demonstrates that the nickel deposit, with or without external rectification, results in a low-stress deposit that is an effective barrier to copper diffusion. Solar cells plated with the boric acid-free nickel bath show good adhesion with passing reliability performance. The study has also shown that both contact and line resistivity to be lower than cells utilizing silver paste. The findings represent a significant value in the removal of boric-acid from the nickel plating process while improving photovoltaic cell performance.



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